

# COM20019I

#### Cost Competitive ARCNET (ANSI 878.1) Controller with 2K x 8 On-Chip RAM

#### **Product Features**

- New Features:
  - Data Rates up to 312.5 Kbps
  - Programmable Reconfiguration Times
- 28 Pin PLCC and 48 Pin TQFP Packages; Leadfree RoHS Compliant Packages also Available
- Ideal for Industrial/Factory/Building Automation and Transportation Applications
- Deterministic, (ANSI 878.1), Token Passing ARCNET Protocol
- Minimal Microcontroller and Media Interface Logic Required
- Flexible Interface For Use With All Microcontrollers or Microprocessors
- Automatically Detects Type of Microcontroller Interface
- 2Kx8 On-Chip Dual Port RAM
- Command Chaining for Packet Queuing
- Sequential Access to Internal RAM
- Software Programmable Node ID

**Data Brief** 

- Eight, 256 Byte Pages Allow Four Pages TX and RX Plus Scratch-Pad Memory
- Next ID Readable
- Internal Clock Scaler for Adjusting Network Speed
- Operating Temperature Range of -40°C to +85°C
- Self-Reconfiguration Protocol
- Supports up to 255 Nodes
- Supports Various Network Topologies (Star, Tree, Bus...)
- CMOS, Single +5V Supply
- Duplicate Node ID Detection
- Powerful Diagnostics
- Receive All Packets Mode
- Flexible Media Interface:
  - RS485 Differential Driver Interface For Low Cost, Low Power, High Reliability

#### **ORDERING INFORMATION**

#### **Order Numbers:**

COM20019ILJP for 28 pin PLCC package; COM20019I-DZD for 28 pin PLCC lead-free RoHS Compliant package COM20019I-HD for 48 pin TQFP package; COM20019I-HT for 48 pin TQFP lead-free RoHS Compliant package



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## **General Description**

SMSC's COM20019I is a member of the family of Embedded ARCNET Controllers from Standard Microsystems Corporation. The device is a general purpose communications controller for networking microcontrollers and intelligent peripherals in industrial, automotive, and embedded control environments using an ARCNET protocol engine. The flexible microcontroller and media interfaces, eight- page message support, and extended temperature range of the COM20019I make it the only true network controller optimized for use in industrial, embedded, and automotive applications. Using an ARCNET protocol engine is the ideal solution for embedded control applications because it provides a deterministic token-passing protocol, a highly reliable and proven networking scheme, and a data rate of up to 312.5 Kbps when using the COM20019I.

A token-passing protocol provides predictable response times because each network event occurs within a predetermined time interval, based upon the number of nodes on the network. The deterministic nature of ARCNET is essential in real time applications. The integration of the 2Kx8 RAM buffer on-chip, the Command Chaining feature, the maximum data rate, and the internal diagnostics make the COM20019I the highest performance embedded communications device available. With only one COM20019I and one microcontroller, a complete communications node may be implemented.

# **Block Diagram**

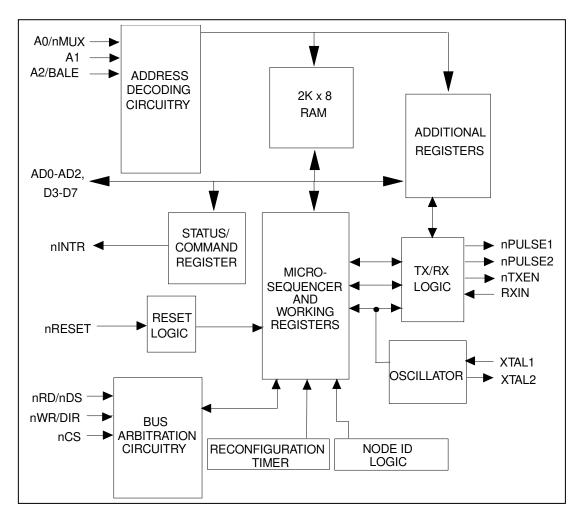
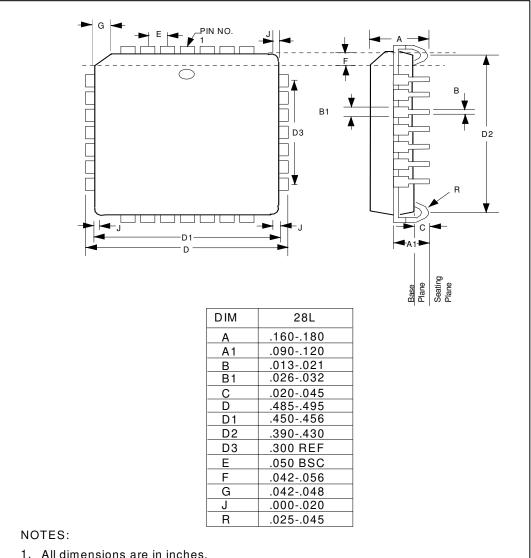


Figure 1 - Internal Block Diagram

## **Package Outlines**

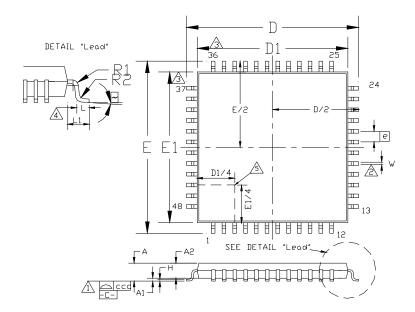


#### 28-Pin PLCC Package Outline and Parameters

1. All dimensions are in inches.

2. Circle indicating pin 1 can appear on a top surface as shown on the drawing or right above it on a beveled edge.

#### 48-Pin TQFP Package Outline and Parameters



|     | MIN        | NOMINAL | МАХ    | REMARK   |
|-----|------------|---------|--------|--|
| Α   | 2          | ~       | 1.6    | Overall Package Height                                     |
| A1  | 0.05       | 0.10    | 0.15   | Standoff   |
| A2  | 1.35       | 1.40    | 1.45   | Body Thickness   |
| D   | 8.80       | 9.00    | 9.20   | X Span   |
| D/2 | 4.40       | 4.50    | 4.60   | <sup>1</sup> / <sub>2</sub> X Span Measure from Centerline |
| D1  | 6.90       | 7.00    | 7.10   | X body Size  |
| E   | 8.80       | 9.00    | 9.10   | Y Span   |
| E/2 | 4.40       | 4.50    | 4.60   | <sup>1</sup> / <sub>2</sub> Y Span Measure from Centerline |
| E1  | 6.90       | 7.00    | 7.10   | Y body Size  |
| Н   | 0.09       | ~       | 0.20   | Lead Frame Thickness                                       |
| L   | 0.45       | 0.60    | 0.75   | Lead Foot Length from Centerline                           |
| L1  | 2          | 1.00    | 2      | Lead Length  |
| е   | 0.50 Basic |         |        | Lead Pitch   |
| θ   | 0°         | ~       | 7°     | Lead Foot Angle  |
| W   | 0.17       | ~       | 0.27   | Lead Width   |
| R1  | 0.08       | ~       | ~      | Lead Shoulder Radius                                       |
| R2  | 0.08       | ~       | 0.20   | Lead Foot Radius   |
| CCC | ~          | ~       | 0.0762 | Coplanarity (Assemblers)                                   |
| CCC | ~          | ~       | 0.08   | Coplanarity (Test House)                                   |

**Note:** Controlling Unit: millimeter